



# BGA/CSP DEVELOPMENT UPDATE SERVICE

## First Quarter, 2001

The first quarterly BGA/CSP update for 2001 features special coverage of the System-on-a-Chip (SoC) versus System-in-Package (SiP) debate, highlighting many SiPs available in BGA or CSP format. A discussion on new BGA packages, including tape, laminate, and ceramic packages, as well as packages for optoelectronic applications are provided. An update on the wafer level package market is provided along with new package introductions and developments. Highlighted are the K&S Flip Chip Division (formerly FCT) Polymer Collar™ Ultra CSP™, Hitachi's WPP2, and a list of wafer level packages in production.

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